

発明名称： ワイヤボンディング

**Bonding wire board provides more circuit connection points while saving the manufacturing cost**

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説明

The present invention discloses a bonding wire board which includes a first board and a second board arranged up and down position, respectively. The first board is formed with a first set of through holes having a first gap. The second board is formed with a second set of through holes having a second gap. The first gap is larger than the second gap. A first set of bonding wires is extended from the first set of through holes to the corresponding second set of through holes. A stuffing material is clipped between the first and the second boards to cover the bonding wires.

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